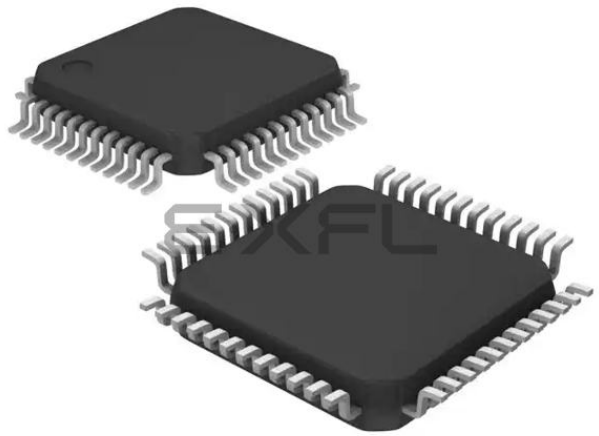

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Applications of "Embedded - Microcontrollers"

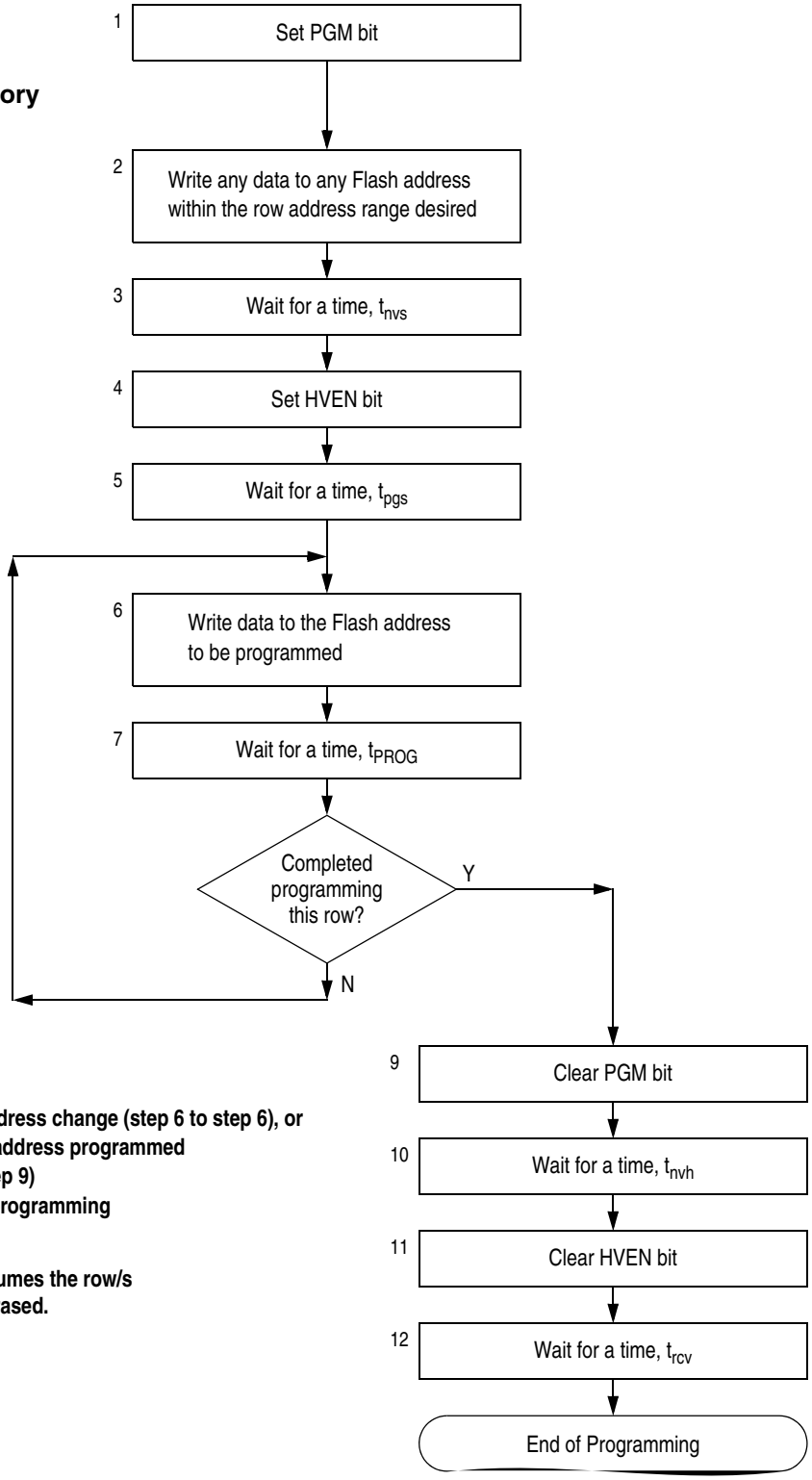
Details	
Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LED, LVD, POR, PWM
Number of I/O	23
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.3V
Data Converters	A/D 12x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mcr908jl3ecfae

Table of Contents

Chapter 9
Analog-to-Digital Converter (ADC)

Chapter 10
Input/Output (I/O) Ports

Algorithm for programming a row (32 bytes) of Flash memory



NOTE:

The time between each Flash address change (step 6 to step 6), or the time between the last Flash address programmed to clearing PGM bit (step 6 to step 9) must not exceed the maximum programming time, t_{PROG} max.

This row program algorithm assumes the row/s to be programmed are initially erased.

Figure 2-5. Flash Programming Flowchart

LVID — Low Voltage Inhibit Disable Bit

1 = Low Voltage Inhibit disabled
0 = Low Voltage Inhibit enabled

SSREC — Short Stop Recovery Bit

SSREC enables the CPU to exit stop mode with a delay of 32 × 2OSCOUT cycles instead of a 4096 × 2OSCOUT cycle delay.

1 = Stop mode recovery after 32 × 2OSCOUT cycles
0 = Stop mode recovery after 4096 × 2OSCOUT cycles

NOTE

Exiting stop mode by pulling reset will result in the long stop recovery.

If using an external crystal, do not set the SSREC bit.

STOP — STOP Instruction Enable

STOP enables the STOP instruction.

1 = STOP instruction enabled
0 = STOP instruction treated as illegal opcode

COPD — COP Disable Bit

COPD disables the COP module. (See Chapter 13 Computer Operating Properly (COP).)

1 = COP module disabled
0 = COP module enabled

3.4 Configuration Register 2 (CONFIG2)

Address: $001E

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	IRQPUD	R	R	LVIT1	LVIT0	R	R	R
Reset:	0	0	0	Not affected	Not affected	0	0	0
POR:	0	0	0	0	0	0	0	0

R = Reserved

Figure 3-2. Configuration Register 2 (CONFIG2)

IRQPUD — $\overline{\text{IRQ}}$ Pin Pull-up control bit

1 = Internal pull-up is disconnected
0 = Internal pull-up is connected between $\overline{\text{IRQ}}$ pin and V_{DD}

LVIT1, LVIT0 — Low Voltage Inhibit trip voltage selection bits

Detail description of the LVI control signals is given in Chapter 14 Low Voltage Inhibit (LVI)

4.3.3 Stack Pointer

The stack pointer is a 16-bit register that contains the address of the next location on the stack. During a reset, the stack pointer is preset to $00FF. The reset stack pointer (RSP) instruction sets the least significant byte to $FF and does not affect the most significant byte. The stack pointer decrements as data is pushed onto the stack and increments as data is pulled from the stack.

In the stack pointer 8-bit offset and 16-bit offset addressing modes, the stack pointer can function as an index register to access data on the stack. The CPU uses the contents of the stack pointer to determine the conditional address of the operand.

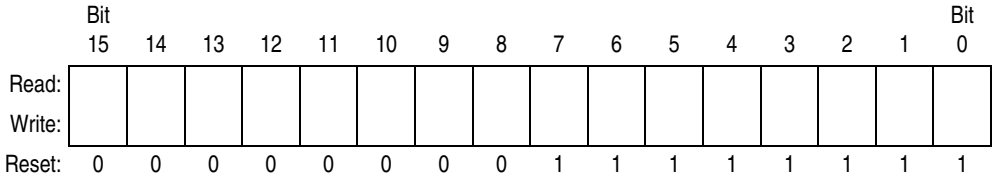


Figure 4-4. Stack Pointer (SP)

NOTE

The location of the stack is arbitrary and may be relocated anywhere in random-access memory (RAM). Moving the SP out of page 0 ($0000 to $00FF) frees direct address (page 0) space. For correct operation, the stack pointer must point only to RAM locations.

4.3.4 Program Counter

The program counter is a 16-bit register that contains the address of the next instruction or operand to be fetched.

Normally, the program counter automatically increments to the next sequential memory location every time an instruction or operand is fetched. Jump, branch, and interrupt operations load the program counter with an address other than that of the next sequential location.

During reset, the program counter is loaded with the reset vector address located at $FFFE and $FFFF. The vector address is the address of the first instruction to be executed after exiting the reset state.

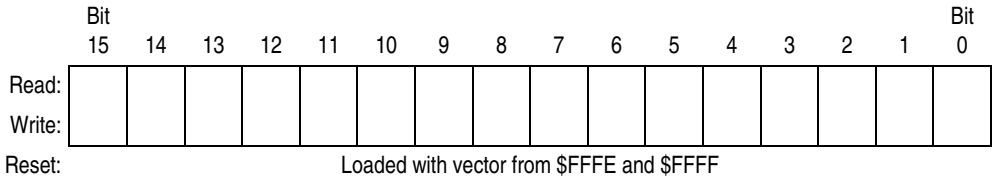


Figure 4-5. Program Counter (PC)

4.3.5 Condition Code Register

The 8-bit condition code register contains the interrupt mask and five flags that indicate the results of the instruction just executed. Bits 6 and 5 are set permanently to 1. The following paragraphs describe the functions of the condition code register.

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	V	1	1	H	I	N	Z	C
Reset:	X	1	1	X	1	X	X	X

X = Indeterminate

Figure 4-6. Condition Code Register (CCR)

V — Overflow Flag

The CPU sets the overflow flag when a two's complement overflow occurs. The signed branch instructions BGT, BGE, BLE, and BLT use the overflow flag.

1 = Overflow
0 = No overflow

H — Half-Carry Flag

The CPU sets the half-carry flag when a carry occurs between accumulator bits 3 and 4 during an add-without-carry (ADD) or add-with-carry (ADC) operation. The half-carry flag is required for binary-coded decimal (BCD) arithmetic operations. The DAA instruction uses the states of the H and C flags to determine the appropriate correction factor.

1 = Carry between bits 3 and 4
0 = No carry between bits 3 and 4

I — Interrupt Mask

When the interrupt mask is set, all maskable CPU interrupts are disabled. CPU interrupts are enabled when the interrupt mask is cleared. When a CPU interrupt occurs, the interrupt mask is set automatically after the CPU registers are saved on the stack, but before the interrupt vector is fetched.

1 = Interrupts disabled
0 = Interrupts enabled

NOTE

To maintain M6805 Family compatibility, the upper byte of the index register (H) is not stacked automatically. If the interrupt service routine modifies H, then the user must stack and unstack H using the PSHH and PULH instructions.

After the I bit is cleared, the highest-priority interrupt request is serviced first.

A return-from-interrupt (RTI) instruction pulls the CPU registers from the stack and restores the interrupt mask from the stack. After any reset, the interrupt mask is set and can be cleared only by the clear interrupt mask software instruction (CLI).

N — Negative Flag

The CPU sets the negative flag when an arithmetic operation, logic operation, or data manipulation produces a negative result, setting bit 7 of the result.

1 = Negative result
0 = Non-negative result

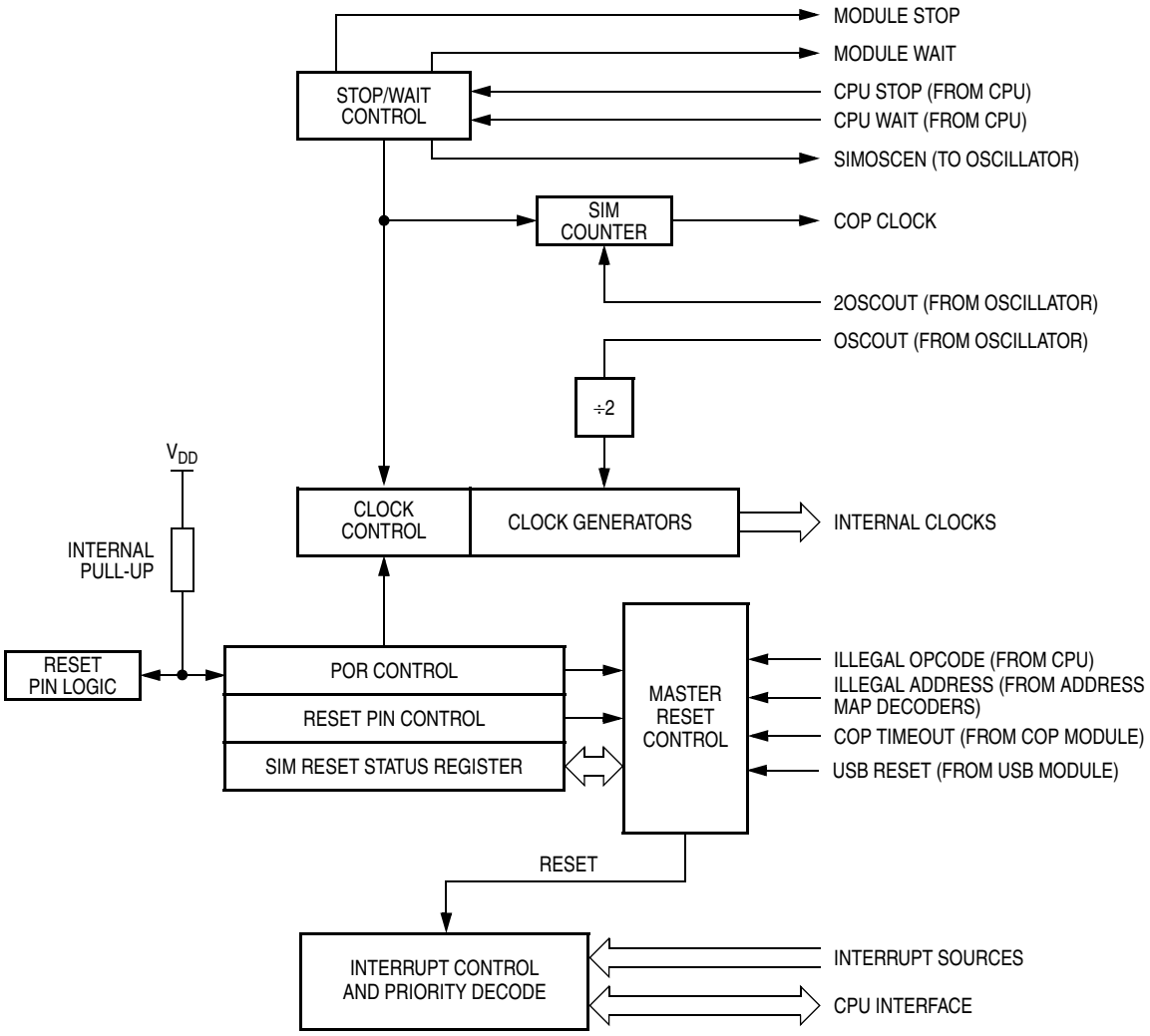


Figure 5-1. SIM Block Diagram

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
$FE00	Break Status Register (BSR)	Read: Write:	R	R	R	R	R	R	SBSW NOTE	R
		Reset:	0	0	0	0	0	0	0	0
Note: Writing a 0 clears SBSW.										
$FE01	Reset Status Register (RSR)	Read: Write:	POR	PIN	COP	ILOP	ILAD	MODRST	LVI	0
		POR:	1	0	0	0	0	0	0	0
$FE02	Reserved	Read: Write:	R	R	R	R	R	R	R	R
		Reset:								
$FE03	Break Flag Control Register (BFCR)	Read: Write:	BCFE	R	R	R	R	R	R	R
		Reset:	0							
			= Unimplemented				R	= Reserved		

Figure 5-2. SIM I/O Register Summary

5.3.2.5 LVI Reset

The low-voltage inhibit module (LVI) asserts its output to the SIM when the V_{DD} voltage falls to the LVI trip voltage V_{TRIP}. The LVI bit in the SIM reset status register (SRSR) is set, and the external reset pin (RSTB) is held low while the SIM counter counts out 4096 2OSCOUT cycles. Sixty-four 2OSCOUT cycles later, the CPU and memories are released from reset to allow the reset vector sequence to occur. The SIM actively pulls down the (RSTB) pin for all internal reset sources.

5.4 SIM Counter

The SIM counter is used by the power-on reset module (POR) and in stop mode recovery to allow the oscillator time to stabilize before enabling the internal bus (IBUS) clocks. The SIM counter also serves as a prescaler for the computer operating properly module (COP). The SIM counter uses 12 stages for counting, followed by a 13th stage that triggers a reset of SIM counters and supplies the clock for the COP module. The SIM counter is clocked by the falling edge of 2OSCOUT.

5.4.1 SIM Counter During Power-On Reset

The power-on reset module (POR) detects power applied to the MCU. At power-on, the POR circuit asserts the signal PORRST. Once the SIM is initialized, it enables the oscillator to drive the bus clock state machine.

5.4.2 SIM Counter During Stop Mode Recovery

The SIM counter also is used for stop mode recovery. The STOP instruction clears the SIM counter. After an interrupt, break, or reset, the SIM senses the state of the short stop recovery bit, SSREC, in the mask option register. If the SSREC bit is a one, then the stop recovery is reduced from the normal delay of 4096 2OSCOUT cycles down to 32 2OSCOUT cycles. This is ideal for applications using canned oscillators that do not require long start-up times from stop mode. External crystal applications should use the full stop recovery time, that is, with SSREC cleared in the configuration register (CONFIG).

5.4.3 SIM Counter and Reset States

External reset has no effect on the SIM counter. (See 5.6.2 Stop Mode for details.) The SIM counter is free-running after all reset states. (See 5.3.2 Active Resets from Internal Sources for counter control and internal reset recovery sequences.)

5.5 Exception Control

Normal, sequential program execution can be changed in three different ways:

- Interrupts
  - Maskable hardware CPU interrupts
  - Non-maskable software interrupt instruction (SWI)
- Reset
- Break interrupts

5.5.1 Interrupts

An interrupt temporarily changes the sequence of program execution to respond to a particular event. Figure 5-8 flow charts the handling of system interrupts.

At the beginning of an interrupt, the CPU saves the CPU register contents on the stack and sets the interrupt mask (I bit) to prevent additional interrupts. At the end of an interrupt, the RTI instruction recovers the CPU register contents from the stack so that normal processing can resume. Figure 5-9 shows interrupt entry timing. Figure 5-10 shows interrupt recovery timing.

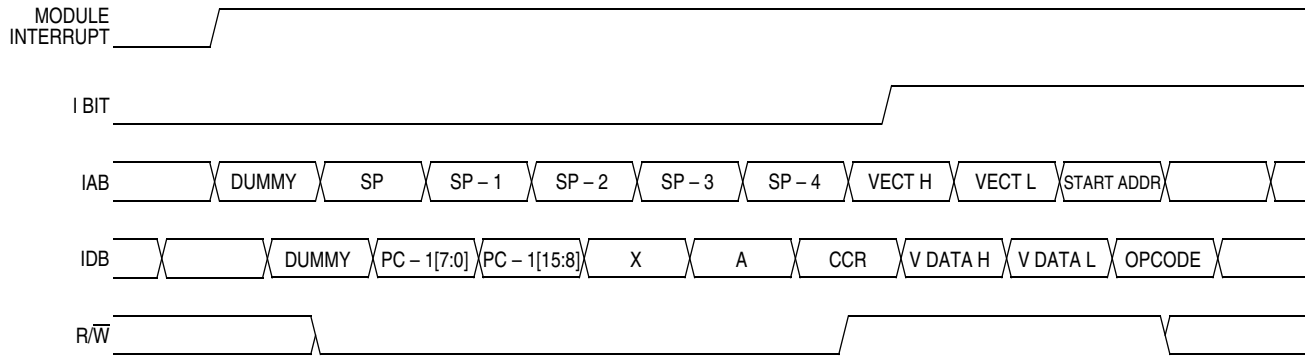


Figure 5-9. Interrupt Entry

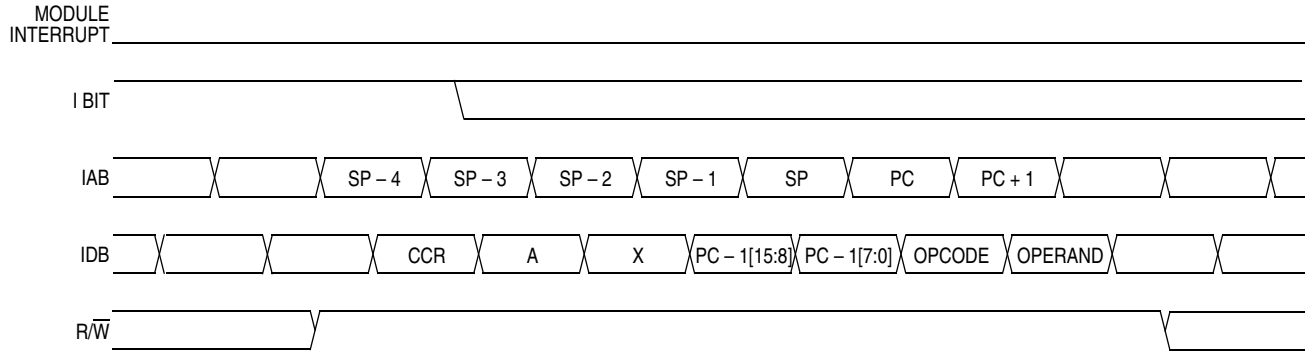


Figure 5-10. Interrupt Recovery

5.5.1.1 Hardware Interrupts

A hardware interrupt does not stop the current instruction. Processing of a hardware interrupt begins after completion of the current instruction. When the current instruction is complete, the SIM checks all pending hardware interrupts. If interrupts are not masked (I bit clear in the condition code register), and if the corresponding interrupt enable bit is set, the SIM proceeds with interrupt processing; otherwise, the next instruction is fetched and executed.

If more than one interrupt is pending at the end of an instruction execution, the highest priority interrupt is serviced first. Figure 5-11 demonstrates what happens when two interrupts are pending. If an interrupt is pending upon exit from the original interrupt service routine, the pending interrupt is serviced before the LDA instruction is executed.

6.4 I/O Signals

The following paragraphs describe the oscillator I/O signals.

6.4.1 Crystal Amplifier Input Pin (OSC1)

OSC1 pin is an input to the crystal oscillator amplifier or the input to the RC oscillator circuit.

6.4.2 Crystal Amplifier Output Pin (OSC2/PTA6/RCCLK)

For the X-tal oscillator device, OSC2 pin is the output of the crystal oscillator inverting amplifier.

For the RC oscillator device, OSC2 pin can be configured as a general purpose I/O pin PTA6, or the output of the internal RC oscillator clock, RCCLK.

Device	Oscillator	OSC2 pin function
MC68HC908JL3E/JK3E/JK1E	X-tal	Inverting OSC1
MC68HRC908JL3E/JK3E/JK1E	RC	Controlled by PTA6EN bit in PTAPUER ($0D) PTA6EN = 0: RCCLK output PTA6EN = 1: PTA6 I/O

6.4.3 Oscillator Enable Signal (SIMOSCEN)

The SIMOSCEN signal comes from the system integration module (SIM) and enables/disables the X-tal oscillator circuit or the RC-oscillator.

6.4.4 X-tal Oscillator Clock (XTALCLK)

XTALCLK is the X-tal oscillator output signal. It runs at the full speed of the crystal (f_{XCLK}) and comes directly from the crystal oscillator circuit. Figure 6-1 shows only the logical relation of XTALCLK to OSC1 and OSC2 and may not represent the actual circuitry. The duty cycle of XTALCLK is unknown and may depend on the crystal and other external factors. Also, the frequency and amplitude of XTALCLK can be unstable at start-up.

6.4.5 RC Oscillator Clock (RCCLK)

RCCLK is the RC oscillator output signal. Its frequency is directly proportional to the time constant of the external R and C. Figure 6-2 shows only the logical relation of RCCLK to OSC1 and may not represent the actual circuitry.

6.4.6 Oscillator Out 2 (2OSCOUT)

2OSCOUT is same as the input clock (XTALCLK or RCCLK). This signal is driven to the SIM module and is used to determine the COP cycles.

6.4.7 Oscillator Out (OSCOUT)

The frequency of this signal is equal to half of the 2OSCOUT, this signal is driven to the SIM for generation of the bus clocks used by the CPU and other modules on the MCU. OSCOUT will be divided again in the SIM and results in the internal bus frequency being one fourth of the XTALCLK or RCCLK frequency.

7.3.6 Commands

The monitor ROM uses the following commands:

- READ (read memory)
- WRITE (write memory)
- IREAD (indexed read)
- IWRITE (indexed write)
- READSP (read stack pointer)
- RUN (run user program)

Table 7-4. READ (Read Memory) Command

Description	Read byte from memory
Operand	Specifies 2-byte address in high byte:low byte order
Data Returned	Returns contents of specified address
Opcode	$4A
Command Sequence	

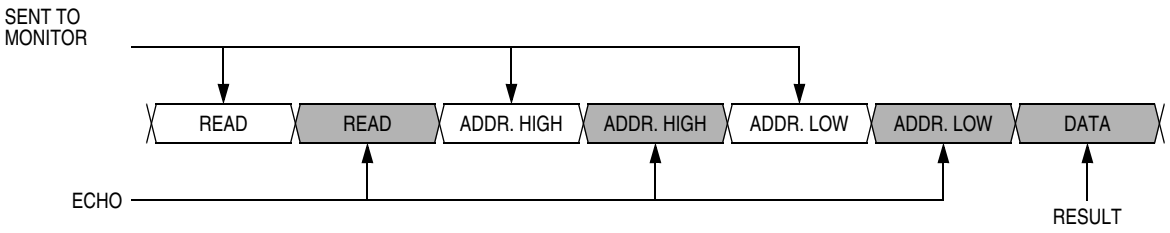
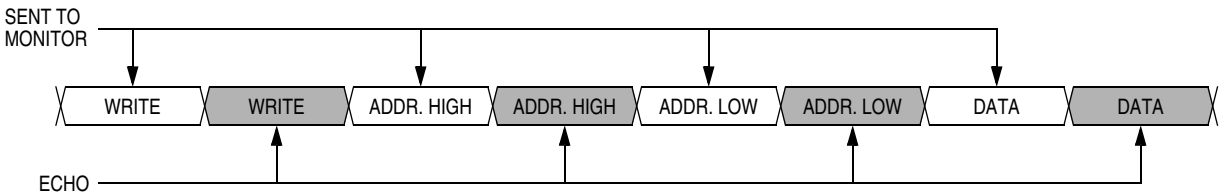


Table 7-5. WRITE (Write Memory) Command

Description	Write byte to memory
Operand	Specifies 2-byte address in high byte:low byte order; low byte followed by data byte
Data Returned	None
Opcode	$49
Command Sequence	



8.9.4 TIM Channel Status and Control Registers (TSC0:TSC1)

Each of the TIM channel status and control registers does the following:

- Flags input captures and output compares
- Enables input capture and output compare interrupts
- Selects input capture, output compare, or PWM operation
- Selects high, low, or toggling output on output compare
- Selects rising edge, falling edge, or any edge as the active input capture trigger
- Selects output toggling on TIM overflow
- Selects 0% and 100% PWM duty cycle
- Selects buffered or unbuffered output compare/PWM operation

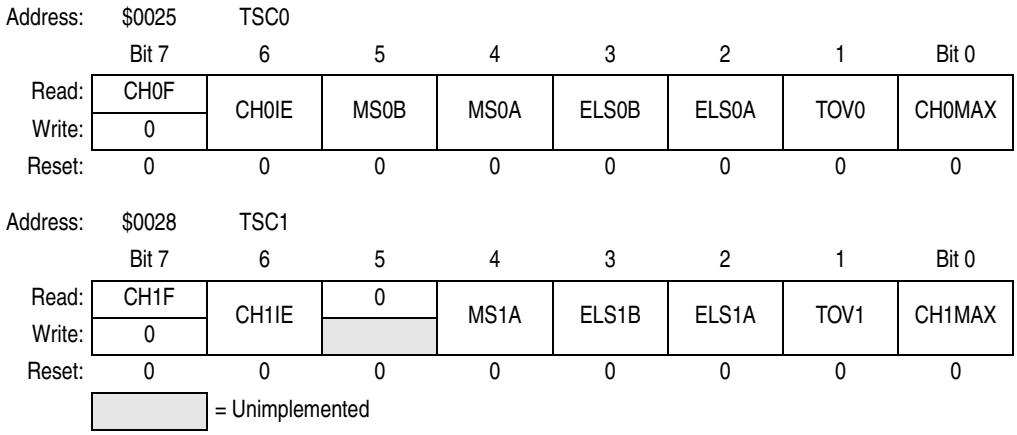


Figure 8-7. TIM Channel Status and Control Registers (TSC0:TSC1)

CHxF — Channel x Flag Bit

When channel x is an input capture channel, this read/write bit is set when an active edge occurs on the channel x pin. When channel x is an output compare channel, CHxF is set when the value in the TIM counter registers matches the value in the TIM channel x registers.

When TIM CPU interrupt requests are enabled (CHxIE=1), clear CHxF by reading the TIM channel x status and control register with CHxF set and then writing a zero to CHxF. If another interrupt request occurs before the clearing sequence is complete, then writing zero to CHxF has no effect. Therefore, an interrupt request cannot be lost due to inadvertent clearing of CHxF.

Reset clears the CHxF bit. Writing a one to CHxF has no effect.

1 = Input capture or output compare on channel x
0 = No input capture or output compare on channel x

CHxIE — Channel x Interrupt Enable Bit

This read/write bit enables TIM CPU interrupt service requests on channel x. Reset clears the CHxIE bit.

1 = Channel x CPU interrupt requests enabled
0 = Channel x CPU interrupt requests disabled

TOVx — Toggle-On-Overflow Bit

When channel x is an output compare channel, this read/write bit controls the behavior of the channel x output when the TIM counter overflows. When channel x is an input capture channel, TOVx has no effect. Reset clears the TOVx bit.

1 = Channel x pin toggles on TIM counter overflow.
0 = Channel x pin does not toggle on TIM counter overflow.

NOTE

When TOVx is set, a TIM counter overflow takes precedence over a channel x output compare if both occur at the same time.

CHxMAX — Channel x Maximum Duty Cycle Bit

When the TOVx bit is at one, setting the CHxMAX bit forces the duty cycle of buffered and unbuffered PWM signals to 100%. As Figure 8-8 shows, the CHxMAX bit takes effect in the cycle after it is set or cleared. The output stays at the 100% duty cycle level until the cycle after CHxMAX is cleared.

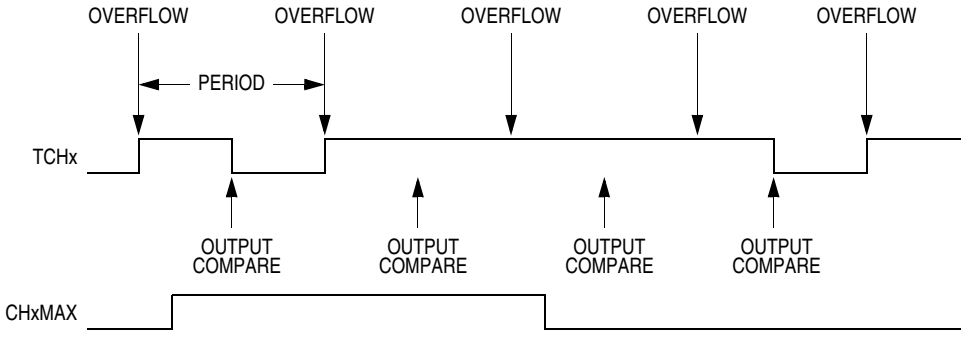


Figure 8-8. CHxMAX Latency

9.3.2 Voltage Conversion

When the input voltage to the ADC equals V_{DD}, the ADC converts the signal to $FF (full scale). If the input voltage equals V_{SS}, the ADC converts it to $00. Input voltages between V_{DD} and V_{SS} are a straight-line linear conversion. All other input voltages will result in $FF if greater than V_{DD} and $00 if less than V_{SS}.

NOTE

Input voltage should not exceed the analog supply voltages.

9.3.3 Conversion Time

Fourteen ADC internal clocks are required to perform one conversion. The ADC starts a conversion on the first rising edge of the ADC internal clock immediately following a write to the ADSCR. If the ADC internal clock is selected to run at 1MHz, then one conversion will take 14μs to complete. With a 1MHz ADC internal clock the maximum sample rate is 71.43kHz.

$$\text{Conversion Time} = \frac{\text{14 ADC Clock Cycles}}{\text{ADC Clock Frequency}}$$

$$\text{Number of Bus Cycles} = \text{Conversion Time} \times \text{Bus Frequency}$$

9.3.4 Continuous Conversion

In the continuous conversion mode, the ADC continuously converts the selected channel filling the ADC data register with new data after each conversion. Data from the previous conversion will be overwritten whether that data has been read or not. Conversions will continue until the ADCO bit is cleared. The COCO bit (ADC status and control register, $003C) is set after each conversion and can be cleared by writing the ADC status and control register or reading of the ADC data register.

9.3.5 Accuracy and Precision

The conversion process is monotonic and has no missing codes.

9.4 Interrupts

When the AIEN bit is set, the ADC module is capable of generating a CPU interrupt after each ADC conversion. A CPU interrupt is generated if the COCO bit is at 0. The COCO bit is not used as a conversion complete flag when interrupts are enabled.

9.5 Low-Power Modes

The following subsections describe the ADC in low-power modes.

9.5.1 Wait Mode

The ADC continues normal operation during wait mode. Any enabled CPU interrupt request from the ADC can bring the MCU out of wait mode. If the ADC is not required to bring the MCU out of wait mode, power down the ADC by setting the ADCH[4:0] bits in the ADC status and control register to 1’s before executing the WAIT instruction.

Chapter 16
Electrical Specifications

16.1 Introduction

This section contains electrical and timing specifications.

16.2 Absolute Maximum Ratings

Maximum ratings are the extreme limits to which the MCU can be exposed without permanently damaging it.

NOTE

This device is not guaranteed to operate properly at the maximum ratings. Refer to 16.5 5V DC Electrical Characteristics and 16.8 3V DC Electrical Characteristics for guaranteed operating conditions.

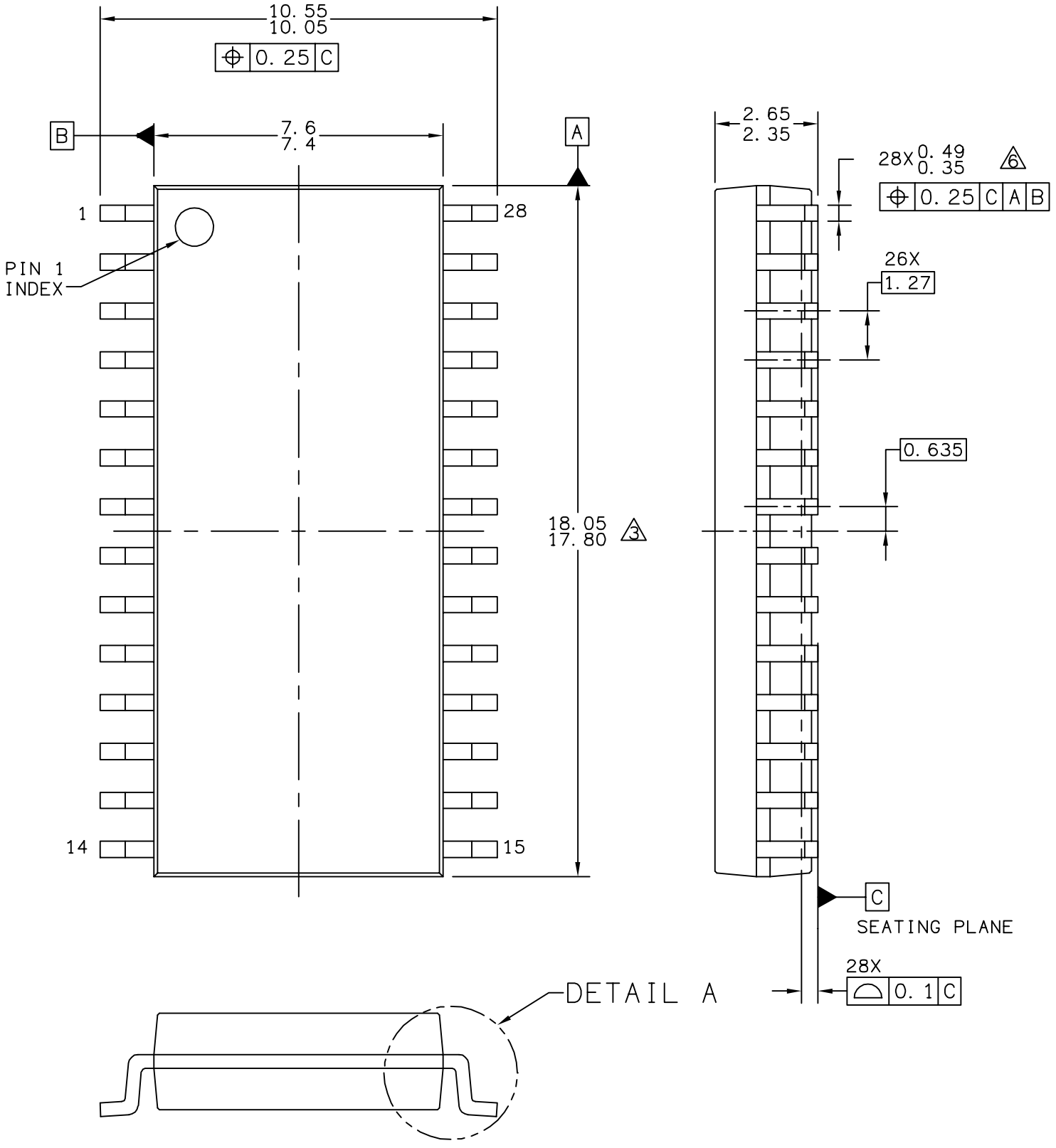
Table 16-1. Absolute Maximum Ratings

Characteristic[1]	Symbol	Value	Unit
Supply voltage	V_{DD}	−0.3 to +6.0	V
Input voltage	V_{IN}	V_{SS}−0.3 to V_{DD} +0.3	V
Mode entry voltage, $\overline{IRQ}$ pin	V_{TST}	V_{SS}−0.3 to +8.5	V
Maximum current per pin excluding V_{DD} and V_{SS}	I	±25	mA
Storage temperature	T_{STG}	−55 to +150	°C
Maximum current out of V_{SS}	I_{MVSS}	100	mA
Maximum current into V_{DD}	I_{MVDD}	100	mA

1. Voltages referenced to V_{SS}.

NOTE

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum-rated voltages to this high-impedance circuit. For proper operation, it is recommended that V_{IN} and V_{OUT} be constrained to the range $V_{SS} \le (V_{IN}$ or $V_{OUT}) \le V_{DD}$. Reliability of operation is enhanced if unused inputs are connected to an appropriate logic voltage level (for example, either V_{SS} or V_{DD}.)



MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE: SOIC, WIDE BODY, 28 LEAD CASEOUTLINE	DOCUMENT NO: 98ASB42345B	REV: G
	CASE NUMBER: 751F-05	10 MAR 2005
	STANDARD: MS-013AE	

A.5.3 Control Timing

Table A-3. Control Timing

Characteristic[1]	Symbol	Min	Max	Unit
Internal operating frequency[2]	f_{OP}	—	2	MHz
$\overline{RST}$ input pulse width low[3]	t_{IRL}	1.5	—	µs

1. V_{DD} = 2.2 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H; timing shown with respect to 20% V_{DD} and 70% V_{DD}, unless otherwise noted.
2. Some modules may require a minimum frequency greater than dc for proper operation; see appropriate table for this information.
3. Minimum pulse width reset is guaranteed to be recognized. It is possible for a smaller pulse width to cause a reset.

A.5.4 Oscillator Characteristics

Table A-4. Oscillator Component Specifications

Characteristic	Symbol	Min	Typ	Max	Unit
Crystal frequency, XTALCLK	$f_{OSCXCLK}$	—	—	8	MHz
External clock reference frequency[1]	$f_{OSCXCLK}$	dc	—	8	MHz
Crystal load capacitance[2]	C_L	—	—	—	
Crystal fixed capacitance[2]	C_1	—	$2 \times C_L$	—	
Crystal tuning capacitance[2]	C_2	—	$2 \times C_L$	—	
Feedback bias resistor	R_B	—	10 MΩ	—	
Series resistor[2], [3]	R_S	—	—	—	

1. No more than 10% duty cycle deviation from 50%
2. Consult crystal vendor data sheet
3. Not Required for high frequency crystals

Appendix B
MC68H(R)C08JL3E/JK3E

B.1 Introduction

This appendix introduces four devices, that are ROM versions of MC68H(R)C908JL3E/JK3E:

- MC68HC08JL3E
- MC68HC08JK3E
- MC68HRC08JL3E
- MC68HRC08JK3E

The entire data book apply to these ROM devices, with exceptions outlined in this appendix.

Table B-1. Summary of Device Differences

	MC68H(R)C08JL3E/JK3E	MC68H(R)C908JL3E/JK3E
Memory ($EC00–$FBFF)	4,096 bytes ROM	4,096 bytes Flash
User vectors ($FFD0–$FFFF)	48 bytes ROM	48 bytes Flash
Registers at $FE08 and $FE09	Not used; locations are reserved.	Flash related registers. $FE08 — FLCR $FF09 — FLBPR
Monitor ROM ($FC00–$FDFF and $FE10–$FFCF)	$FC00–$FDFF: Not used. $FE10–$FFCF: Used for testing purposes only.	Used for testing and Flash programming/erasing.

B.2 MCU Block Diagram

Figure B-1 shows the block diagram of the MC68H(R)C08JL3E/JK3E.

B.8 MC Order Numbers

These part numbers are generic numbers only. To place an order, ROM code must be submitted to the ROM Processing Center (RPC).

Table B-6. MC Order Numbers

MC Order Number	Oscillator Type	Package
MC68HC08JL3ECP MC68HC08JL3EMP MC68HC08JL3ECDW MC68HC08JL3EMDW	Crystal	28-pin package
MC68HRC08JL3ECP MC68HRC08JL3EMP MC68HRC08JL3ECDW MC68HRC08JL3EMDW	RC	
MC68HC08JK3ECP MC68HC08JK3EMP MC68HC08JK3ECDW MC68HC08JK3EMDW	Crystal	20-pin package
MC68HRC08JK3ECP MC68HRC08JK3EMP MC68HRC08JK3ECDW MC68HRC08JK3EMDW	RC	

NOTES:
C = –40 °C to +85 °C
M = –40 °C to +125 °C (available for V_{DD} = 5V only)
P = Plastic dual in-line package (PDIP)
DW = Small outline integrated circuit package (SOIC)